

QBiX-JMB-ADLA67EHG-B1

Industrial system with Intel® Q670E Chipset, support for Intel® 14th/13th/12th Gen Processors and Discrete GFX card



Features

- System Size : 224W x 368D x 166.3H(mm) - Discrete GFX card support (Optional)
- Support Intel® 14th/13th/12th Gen Processor
- Dual Channel DDR4, 2 x SO-DIMMs
- DVI-D, VGA & DP ports for multiple display
- 1 x 2.5GbE LAN Port
- 3 x GbE LAN Ports
- 4 x COM Ports
- 10 x USB Ports

Audio	Realtek® ALC897
Storage	4 x 2.5" HDD/SSD (SATA 6Gb/s)
Raid	RAID 0/1/5/10
Expansion Slots	1 x 2280 M.2 M-Key (PCIe Gen4x4) 1 x 2230 M.2 E-Key 1 x Full-size mini PCIe with SIM slot 1 x PCIe slot -- Discrete riser card support
Front I/O	1 x Power Switch/Power/HDD LED 3 x Audio Jacks (Line in, Line out, Mic in) 1 x Display Port/1 x DVI-D/1 x VGA 2 x COM Ports (RS-232/422/485 & RI/5V/12V) 2 x COM Ports (RS-232) 4 x RJ45 LAN Ports 2 x USB 3.2 Gen 2x1 2 x USB 3.2 Gen 1 6 x USB 2.0 1 x 4-pin Terminal Block 2 x External Antenna Holes (Optional)
Riser card (optional)	1 x PCIe x4 (Gen3 x4) 2 x PCIe x16 — Single at Gen3 x16 only or — Dual at Gen3 x8 + Gen3 x8
Power	+24V~48VDC (Full Range) -- Support discrete GFX card
Operation temperature	For Main system : Operating temperature: -20°C to 50°C (CPU TDP 65W) Operating temperature: -20°C to 60°C (CPU TDP 35W) For Full system : Depends on the Graphic cards installed in the system Operating humidity: 0-90% (non-condensing) Non-operating temperature: -40°C to 85°C Non-operating humidity: 0%-95% (non-condensing) Use wide temperature range memory and storage
Vibration During Operation	Operation: IEC 60068-2-64, 1 Grms, random, 5 ~ 500 Hz, 1 hr / Per Axis, with SSD/M.2 2280 & Without Graphics Cards Non-operation: IEC 60068-2-6, 2 G, Sine, 10 ~ 500 Hz, 1 Oct/min, 1 hr / Per Axis
Shock During Operation	Operation: IEC 60068-2-27, 50 G, half sine, 11 ms duration, With SSD

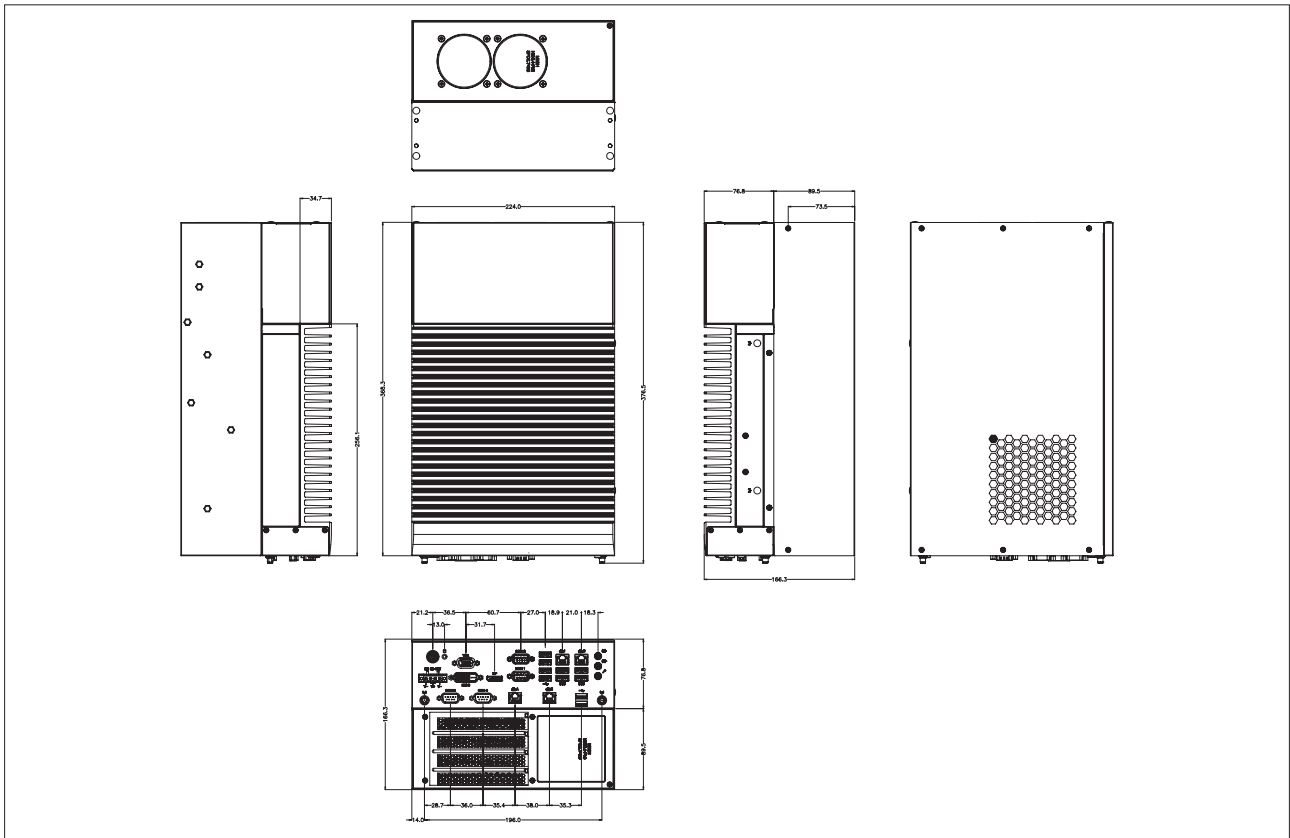
Specifications

Dimension	224W x 368D x 166.3H(mm) - Discrete GFX support (Optional)
CPU	Support for 14th/13th/12th Generation Intel® Core™ i9/i7/i5/i3, Pentium® and Celeron® processors in the LGA1700 package TDP under 65W
Chipset	Intel® Q670E Express Chipset
Memory	2 x DDR4 SO-DIMM sockets, Max. Capacity 64GB Support Dual channel DDR4 3200 MHz memory modules
Ethernet	1 x 2.5GbE LAN Port (Intel® I226V) 1 x GbE LAN Port (Intel® I219LM, Vpro support) 2 x GbE LAN Ports (Intel® I211AT)
Graphic support	Integrated Graphics Processor - depends on CPU: 1 x DP port, supporting a maximum resolution of 4096x2160 @60Hz 1 x DVI-D port, supporting a maximum resolution of 1920x1080 @60Hz 1 x VGA port, supporting a maximum resolution of 1920x1080 @60Hz (3 independent display outputs)

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Dimension

Unit: mm



Packing Content

For Main system : 9BQJQ67EAMR-SI

- Carton size: 351 x 300 x 166 (mm)
 - Packing Capacity: 1pc
 - Including:
 - Terminal Blocks Male Plug x 1 (P/N: 25I00-2ESDV0-D2R)
 - Screw M3x4L x 16 (P/N : 25984G-1C014-S00)
- *Quantity of the HDD screws in the accessory kit may decreased based on actual HDD assemble quantity.

For Expansion slot kit : 6BQJH310BPR-SI

- Carton size: 460 x 315 x 279 (mm)
- Packing Capacity: 1pc
- Including:
 - Screw #6-32x4L x16 (P/N: 25KS2-13004F-S0R)

Order Information

- System: 9BQJQ67EAMR-SI & 6BQJH310BPR-SI (Box packing)
(Built in Components: Please contact with your sales representative for more information or e-mailed to : sales@gigaipc.com)

Optional Kit

- TPM 2.0 module P/N: 9CTM000NR-00

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